

LTCC DIRECTIONAL **COUPLERS**



DATA SHEET D3FL10F 10.05.2010

FEATURES

- Low Profile Surface Mount Package
- High Power
- Low Insertion Loss
- High Isolation
- RoHS Compliant
- Tape and Reel available for High Volume Production Switch Networks
- 100% RF Tested

APPLICATIONS

- Power Amplifiers
- Power Monitors
- Reflectometers
- Signal Distribution Networks
- Antenna Feeds
- Phase Shifters

GENERAL DESCRIPTION

The D3FL10F is a high performance directional coupler in a surface mount package. This low profile coupler handles up to 20 watts of CW power. The D3FL10F is designed for those demanding applications where high power, low loss and excellent directivity are required.

The D3FL10F is manufactured with materials that have thermal expansion characteristics compatible with industry standard board materials like RO3003, RO4350, FR4 and others. The couplers are available in a RoHS complaint finish and packaged in tape and reel.

ELECTRICAL SPECIFICATIONS*

Frequency MHz	Coupling (dB)	Directivity dB (min)	Insertion Loss dB (max)	VSWR (max)	Power Handling Watts CW	Operating Temperature °C
2100-2400	10 ± 0.8	20	0.5	1.2	20	-55 to +125

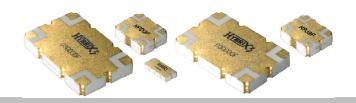
Specification Notes:

* Measured on Florida RF Labs test fixture. Specifications are subject to change without notice.





LTCC DIRECTIONAL COUPLERS

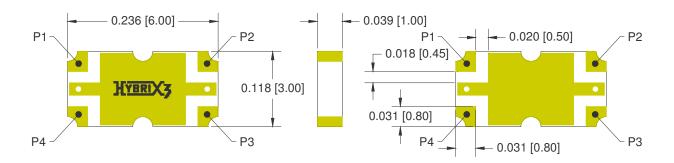


DATA SHEET **D3FL10F**

10.05.2010

COUPLER PIN CONFIGURATION AND MECHANICAL OUTLINE

PORTS	P1	P2	P3	P4
P1	-	OUT	ISO	COUP
P2	OUT	-	COUP	ISO
P3	ISO	COUP	-	OUT
P4	COUP	ISO	OUT	-



COMMONLY USED ATTACHMENT MATERIALS

Material	Composition	Thermal Conductivity (Watts/cm/°C)	Melting Temperature (°C)	
Gold-Tin Solder	80% Gold / 20% Tin	0.58	280	
Lead-Free Solder	99.3% Tin – 0.7% Copper	N/A	227	
Lead-Free Solder	96.5% Tin / 3.5% Silver	0.33	221 217 - 220	
Lead-Free Solder	96.5% Tin / 3% Silver / 0.5% Copper	N/A		
Sn63 Solder	63% Tin / 37% Lead	0.49	183	
Conductive Epoxy	Silver Filled	0.01 to 0.29	N/A	

